

High-Efficiency, Step-Down DC/DC Controller

FEATURES

- High Efficiency (up to 95%).
- Low Quiescent Current at 90μA.
- Pulse-Skipping and Pulse-Frequency Modulation.
- Inputs-Uncommitted Current Sense Comparator.
- Duty Cycle Adjustable.
- 90KHz to 280KHz Oscillator Frequency.
- Power-Saving Shutdown Mode (8μA Typical).
- Push-Pull Driver Output.

APPLICATIONS

- LCD Monitors
- Notebook Computers
- Step-Down DC/DC Controller Module.
- Constant Current Source for Battery Chargers.

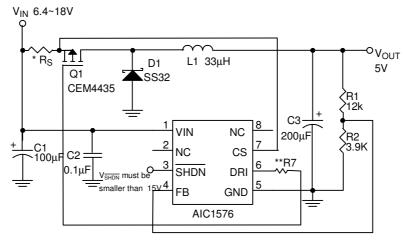
DESCRIPTION

The AIC1576 is a high performance step-down DC/DC controller, designed to drive an external P-channel MOSFET to generate programmable output voltages. Two main schemes of Pulse-Skipping and Pulse-Frequency Modulation are employed to maintain low quiescent current and high conversion efficiency under wide ranges of input voltage and loading condition. The AIC1576 delivers 10mA to 2A of output current with 87%~93% efficiency at V_{IN}=9V, V_{OUT}=5V condition. A current sense comparator with both inverting and non-inverting input uncommitted is included to provide the crucial function of either current limit protection or constant output current control. The efficiency of AIC1576 is typically greater than 90%. Quiescent current is about 90µA and can be reduced to 8µA in shutdown mode. Switching frequency being in around 90KHz to 280KHz range, small size switching components are ideal for battery powered portable equipment.

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■ TYPICAL APPLICATION CIRCUIT



* R_S should not be omitted so that inrush current won't be too high.

$$I_{P} = I_{O,MAX} + \frac{Vout(Vin - Vout)}{2Vin \times f_{S} \times L}$$

$$R_{S} = \frac{0.9 \times V_{TH,MIN}}{I_{P}} = \frac{45mV}{I_{P}} = \frac{0.09V_{IN}f_{S}L}{2V_{IN}f_{S}LI_{O,MAX} + V_{IN}V_{OUT} - V_{OUT}^{2}}$$

V_{IN}: Input voltage V_{OUT}: Output voltage f_S: Working frequency L= Inductor value

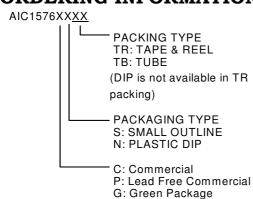
I_{O,MAX}: Maximum Output current

V_{TH,MIN}: Minimum Current Limit Sense Threshold

**V_{IN}>15V, R7=15Ω V_{IN}≤15V, R7=0Ω

DC/DC Buck Converter

ORDERING INFORMATION



PIN CONFIGURATION

SOP-8 / DIP-8
TOP VIEW

VIN 1

NC 2

SHDN 3

FB 4

5 GND

Example: AIC1576CSTR

→ in SO-8 Package & Taping & Reel Packing Type

AIC1576PSTF

→ in SO-8 Lead Free Package & Taping & Reel Packing Type



■ ABSOLUTE MAXIMUM RATINGS

VIN Supply Voltage	18V
SHDN Voltage	15V
Operating Temperature Range	-40°C ~ 85°C
Junction Temperature Range	125°C
Thermal Resistance Junction to Case DIP8	60°C/W
SOP8	40°C/W
Thermal Resistance Junction to Ambient DIP8	100°C/W
(Assume no ambient airflow, no heatsink) SOP8	160°C/W
Storage Temperature Range	-65°C ~ 150°C
Lead Temperature (Soldering 10 Sec)	260°C

Absolute Maximum Ratings are those values beyond which the life of a device may be Impaired.

■ TEST CIRCUIT

Refer to TYPICAL APPLICATION CIRCUIT.



■ ELECTRICAL CHARACTERISTICS

(V_{IN}= 13V, T_A=25°C, unless otherwise specified.) (Note 1)

PARAMETERS	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Operation Voltage		4		18	V
Quiescent Current	V _{FB} = 1.5V		90	160	μΑ
Shutdown Mode Current	VSHDN = 0V		8	20	μΑ
Internal Reference Voltage		1.195	1.22	1.245	V
Driver Sinking "ON Resistance"			16		Ω
Driver Sourcing "ON Resistance"			11		Ω
Current Limit Sense Threshold		50	70	90	mV
Shutdown Threshold		0.6	0.9	1.2	V
SHDN Pin Leakage Current	V _{SHDN} < 15V			1	μΑ
Duty Cycle		70	75	80	%
Oscillator Frequency			225		KHz

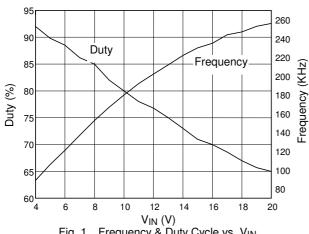
Note 1 : Specifications are production tested at TA = 25°C. Specifications over the -40°C to 85°C operating

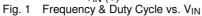
Temperature range are assured by design, characterization and correlation with Statistical

Quality Controls (SQC).



■ TYPICAL PERFORMANCE CHARACTERISTICS





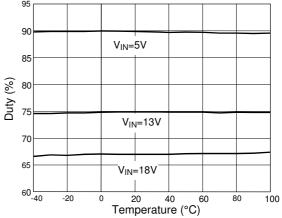


Fig. 2 Duty Cycle vs. Temperature

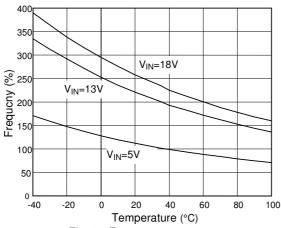
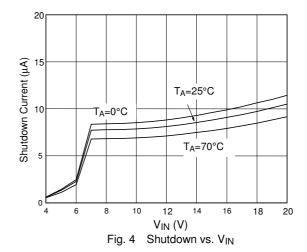


Fig. 3 Frequency vs. Temperature



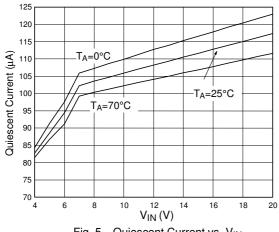


Fig. 5 Quiescent Current vs. V_{IN}



■ BLOCK DIAGRAM

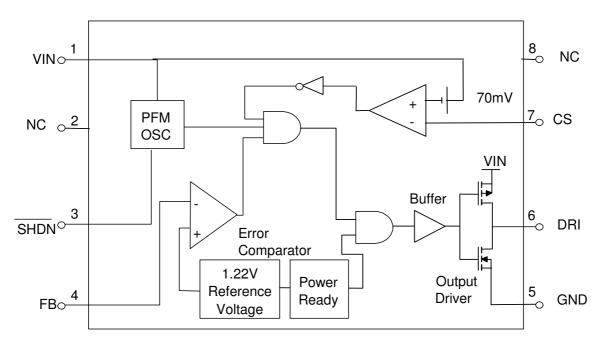


Fig.6 Current Limit Comparator

PIN DESCRIPTIONS

PIN 1: VIN - Input supply voltage, ranged from 4V to 18V is recommended.

PIN 2: NC - No connect.

PIN 3: SHDN- Logical input to shutdown the chip:

 $V_{\overline{SHDN}}$ = High for normal

operation. $V_{\overline{SHDN}}$ = Low for shutdown.

This pin should not be floating or be forced to over 15V. In shutdown mode DRI pins is at

high level.

PIN 4: FB - Feedback comparator input, to compare the feedback voltage with the internal reference voltage. Connecting a resistor R1

to converter output node and a resistor R2 to ground yields the output voltage:

 $V_{OUT}=1.22 x (R1+R2)/R2$

PIN 5: GND - Power ground.

PIN 6: DRI - Push-pull driver output to drive

an external P-channel MOSFET or PNP transistor. When driving a PNP bipolar transistor, a base resistor and a capacitor to the base of PNP are recommended.

PIN 7: CS - Current sense comparator inverting input. This pin voltage

should go over 2V but not to

exceed V_{IN} voltage.

PIN 8: NC - No connect.



APPLICATION INFORMATION

Short Circuit Protection Design

1. As we know, Short Circuit Protection (abbreviated as SCP) does not always exist in the DC-DC converter circuit. The fact is usually the DC-DC converter provides the circuits attached to VOUT with low power or low voltage. Sometimes it has less concern about safety. And its probability of short-circuit is quite low. That gives users reasons to ignore the use of SCP circuit. However, we would still like to point out the importance of the protection. With SCP, the system will be well protected in any situation. Two SCP circuits are introduced as follows for your reference.

2. Design1: shown as Fig. 7.

Method: Add a fast fuse to V_{OUT}.

Fuse select guide: Fuses, which can take the start up current, and break down fast on unexpected current.

Note: Replacement of fuse is needed after short circuit.

Design 2: shown as Fig. 8.Method: Add a SCP circuit

Note:

- 1. The time constant, which is directly related to R1 and C1, has a serious effect on the circuit.
- 2. Circuit can be recovered by removing the short circuit event from the system.
- 3. The condition for applying this design is $V_{OUT} \ge 3V$.

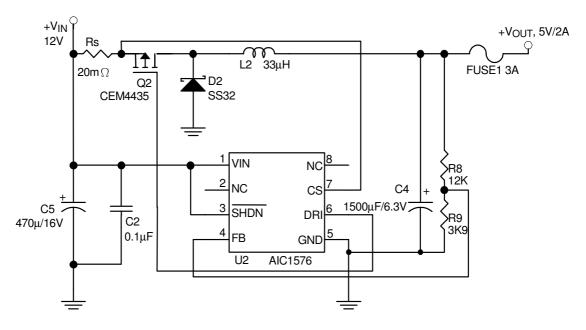


Fig 7. Add a Fast Fuse Solution



■ APPLICATION INFORMATION (Continued)

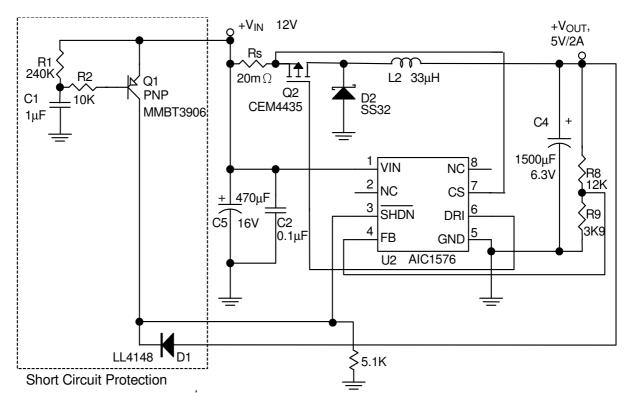


Fig 8. Add A Short Circuit Protection Circuit Solution



APPLICATION EXAMPLES

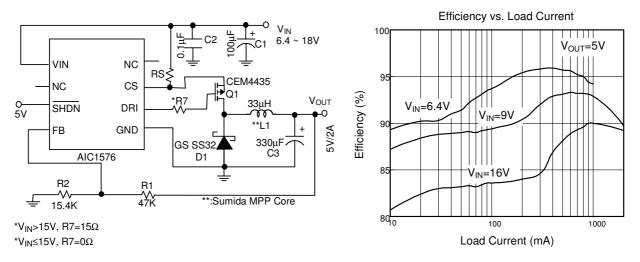


Fig. 9 5V Step-Down Converter

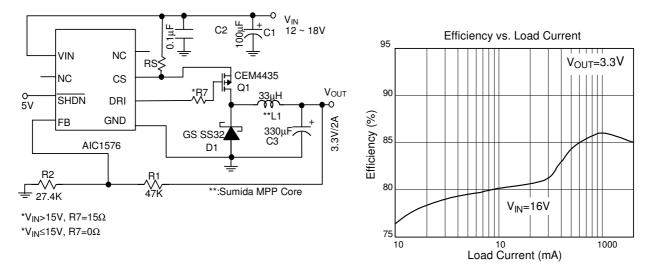
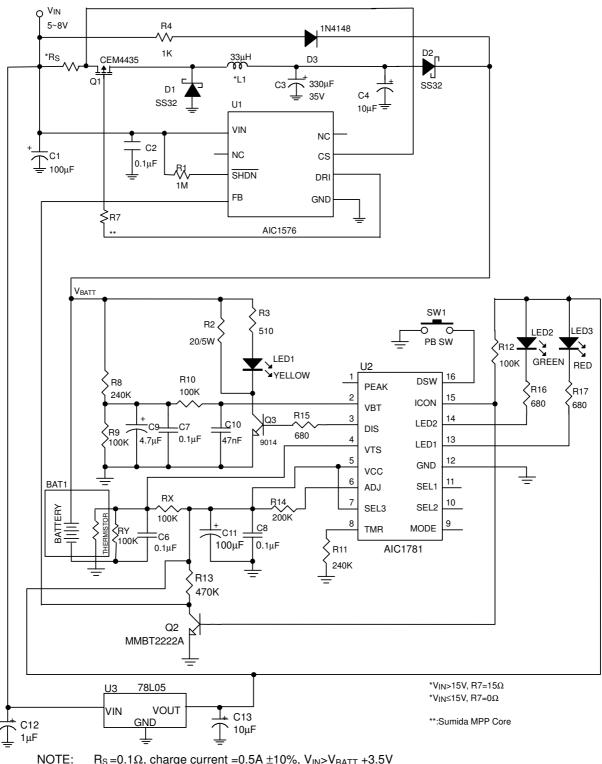


Fig. 10 3.3V Step-Down Converter



■ APPLICATION EXAMPLES (Continued)



NOTE:
$$\begin{split} \text{R}_\text{S} = & 0.1\Omega\text{, charge current} = & 0.5\text{A} \pm 10\%\text{, V}_\text{IN} \text{>V}_\text{BATT} + 3.5\text{V} \\ \text{R}_\text{S} = & 0.05\Omega\text{, charge current} = & 1.4\pm 10\%\text{, V}_\text{IN} \text{>V}_\text{BATT} + 4\text{V} \\ \text{R}_\text{S} = & 0.033\Omega\text{, charge current} = & 1.5\text{A} \pm 10\%\text{, V}_\text{IN} \text{>V}_\text{BATT} + 4.5\text{V} \end{split}$$

3~5 NiMH/NiCd Cells

Fig. 11 Battery Charge Circuit with High-Side Current Sensing Constant Current Source



■ APPLICATION EXAMPLES (Continued)

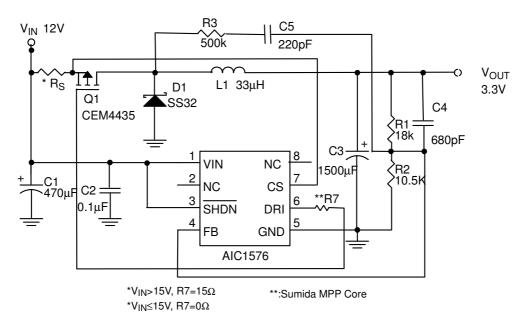
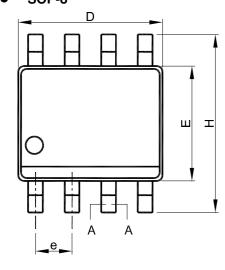


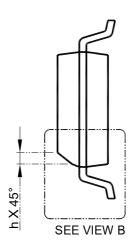
Fig. 12 Step-Down Converter

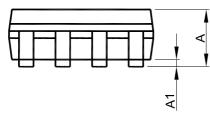


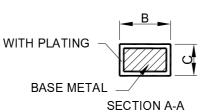
■ PHYSICAL DIMENSIONS (unit: mm)

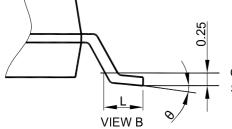
• SOP-8











GAUGE PLANE SEATING PLANE

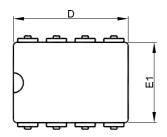
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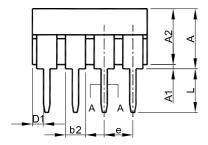
- 2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 6 mil per side .
- 3. Dimension "E" does not include inter-lead flash or protrusions.
- 4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

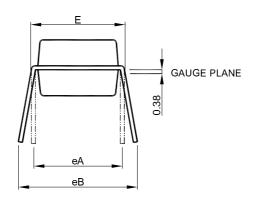
S Y	SOP-8		
М В О	MILLIMETERS		
O L	MIN.	MAX.	
Α	1.35	1.75	
A1	0.10	0.25	
В	0.33	0.51	
С	0.19	0.25	
D	4.80	5.00	
Е	3.80	4.00	
е	1.27 BSC		
Н	5.80	6.20	
h	0.25	0.50	
L	0.40	1.27	
θ	0°	8°	

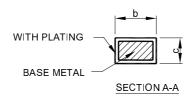


DIP-8









S Y	DIP-8		
M B	MILIIMETERS		
0 L	MIN.	MAX.	
Α		5.33	
A1	0.38		
A2	2.92	4.95	
b	0.36	0.56	
b2	1.14	1.78	
С	0.20	0.35	
D	9.01	10.16	
D1	0.13		
Е	7.62	8.26	
E1	6.10	7.11	
е	2.54 BSC		
eА	7.62 BSC		
еВ		10.92	
L	2.92	3.81	

Note: 1. Refer to JEDEC MS-001BA

- 2. Dimension "D" does not include mold flash, protrusions or gate burrs. Mold flash, protrusion or gate burrs shall not exceed 10 mil per side.
- 3. Dimension "D1" and "E1" do not include inter-lead flash or protrusions.
- 4. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.

Note:

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